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## LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT

2823

ATTY. DOCKET NO.: P69578US0 GROUP ART UNIT: Not Yet Assigned  
 SERIAL NO.: New Application 10/800704 FILING DATE: March 16, 2004  
 APPLICANT(S): Chan Woo PARK, et al. TODAY'S DATE: March 16, 2004

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## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	INT'L CLASS	SUB- CLASS	FILING DATE (If Appropriate)	
<i>APR</i>	AA	5,751,156	05/12/98	Muller et al.	G01R	19/00	06/07/95
<i>APR</i>	AB	6,447,663	09/10/02	Lee et al.	C25D	5/18	10/24/00

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## U.S. PATENT APPLICATION PUBLICATIONS

	PUBLICATION NUMBER	DATE	NAME	INT'L CLASS	SUB- CLASS	FILING DATE (If Appropriate)	
<i>APR</i>	AC	2002/0168810	11/14/02	Jackson	H01L	21/00	03/29/02

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## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>APR</i>	AD	M.A. Reed, et al.; "Conductance of a Molecular Junction"; Science; Vol. 278; October 10, 1997; pp. 252-254.
<i>APR</i>	AE	Hongkun Park, et al.; "Fabrication of metallic electrodes with nanometer separation by electromigration"; Applied Physics Letters; Volume 75, Number 2; July 12, 1999, pp. 301-303. ; July 1998;
<i>APR</i>	AF	Michael Austin, et al.; "Fabrication of nanocontacts for molecular devices using nanoimprint lithography"; J. Vac. Sci. Technol. B; Vol. 20, No. 2; Mar/Apr 2002; pp.665-667.
<i>APR</i>	AG	A.F. Morpurgo, et al.; "Controlled fabrication of metallic electrodes with atomic separation"; Applied Physics Letters; Volume 74, Number 14; April 5, 1999; pp. 2084-2086.
<i>APR</i>	AH	Y.V. Kervennic, et al.; "Nanometer-spaced electrodes with calibrated separation"; Applied Physics Letters; Volume 80, Number 2; January 14, 2002; pp. 321-323.

EXAMINER

DATE CONSIDERED

*Nyibelle Estrade*

*8/2/05*

\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).